

Title (en)

POLYAMIDE BASED LAMINATING, COVERLAY, AND BOND PLY ADHESIVE WITH HEAT ACTIVATED CURE COMPONENT

Title (de)

LAMINATE-, DECKLAGE- UND BUNDSCHICHT-KLEBSTOFF AUF BASIS VON POLYAMID MIT WÄRMEAKTIVIERBAREN HÄRTUNGSKOMPONENTE

Title (fr)

ADHESIF DE COMPLEXAGE, DE COUCHES DE REVETEMENT ET DE COUCHES DE LIAISON A BASE DE POLYAMIDE AYANT UN COMPOSANT A DURCISSEMENT ACTIVE PAR LA CHALEUR

Publication

**EP 0882108 A1 19981209 (EN)**

Application

**EP 97907743 A 19970221**

Priority

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Abstract (en)

[origin: WO9731078A1] A high performance laminating, coverlay, and bond ply adhesive which includes a high molecular weight acid terminated thermoplastic polyamide resin, an epoxy, and a high molecular weight polyester component which can be heat cured with silane and aziridine curatives to form an extremely high temperature resistant, flexible, and high bond strength adhesive is disclosed. The adhesive can be used to enhance the characteristics of polyester and polyethylene naphthalate films for use in flexible and rigid board circuitry applications as well as being an excellent adhesive for films such as polyimide for the same applications thus allowing the films to be used at temperature which are capable of withstanding high temperatures. Along with being useful as laminating adhesive, the system is stable at room temperature and thus can be stored as a free film bond ply adhesive or coated on a film for future conversion into laminate or coverlaying of electronic circuitry.

IPC 1-7

**C09J 177/12**; C09J 167/02; C08G 69/44; C08L 63/00; C09J 163/00; C08G 81/00; C09J 201/10

IPC 8 full level

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CPC (source: EP KR)

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